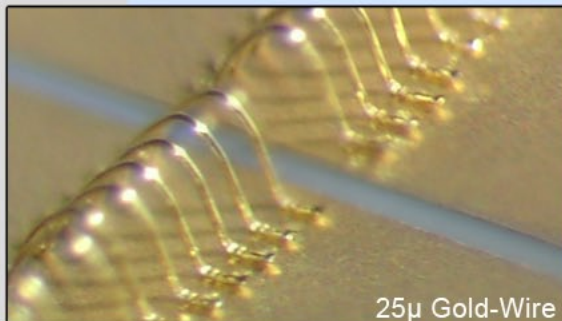




HB12 Wedge Bonder



25µ Gold-Wire



TFT Touch-Panel

- + 17µ to 50µ Wire and 25µ x 200µ Ribbon
- + 6,5" TFT Touchpanel operation System
- + Deep-access Bondhead 16mm
- + Bond arm length 165 mm
- + 100 Program storage capacities
- + Heater stage Controller
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized Y travel for Step-Back loop control
- + Motorized 2" Wire Spool Holder
- + 6:1 ratio X-Y manipulator
- + High/Low Ultrasonic Selector 1 or 2 watt
- + FDD 3,25" to store Bonding programs
- + Loop Profile Programmable
- + Stitch bonding
- + Semi-auto, Step and Manual Bonding Mode

HB12 Thermosonic Wedge Bonder

The HB12 is a bench top size wire bonder, easy to operate and ideal for laboratories, pilot and pre-production runs and small scale production lines.

One Bond head for wire and ribbon bonding in Wedge/Wedge or Stitch bonding mode.

No hardware change necessary. Easy operation with TFT Touch Panel Operator System.

Standard

6,5" TFT Touch panel operation System
90° Bonding Deep-access Bond Head
PLL Control Ultrasonic generator
High/Low Ultrasonic Power Selector (1/2 watt)
Wire and Ribbon bonding
Stitch bonding
Bond arm length 165 mm
100 Program storage capacities
FDD 3,25" to store Bonding programs
Built in Dual Fiber Optic illuminator
Built in Heater stage Controller
Motorised 2" Wire Spool
Motorised Z & Y
Semi-automatic Step and manual bonding
Lopp Profile Software

Options

H10 Zoom Stereo-Microscope Leica S6 20x
H21 100 x 100 mm Adjustable height heated work stage
H26 Adjustable height heated work stage surface 60 mm ø
H29 Adjustable height heated work stage surface 90 mm ø
H30 Additional Soft & Hardware for Ball Bonding
H40 Tool Heater and Temperature Controller
with LCD Display
H50 Spot light targeting System
H51 Manual Z control
H60 Bonding tool for Wedge bonding 25µ wire
H70 Gold-Wire 25µ, 60 Meter, 2" Spool
H72 ½ " Wire Spool adapter
H73 Torque Wrench 25 cNm for Bonding Tool
H90 Delivery with installation and 1 day Training

Technical Specifications

Ultrasonic system	PLL Control 62 kHz transducer
Ultrasonic power	0 - 1 watt Low / 0 - 2 watt High output
Bond time	15 - 2000 msec.
Bond force	15 - 150 cNm
Bonding Tool	1,58 Dia. X 19 mm length (0,0624" Dia. x 0,75")
Gold wire diameter	12,5 to 75µ (0,5 to 3 mil)
Aluminium wire diameter	17 to 75µ (0,5 to 3 mil)
Gold ribbon	up to 25 x 200µ
Motorised Wire Spool	50,8 mm (2 inch)
Wire termination	Table tear or Bondhead tear
Wire feed angle	90° for Wire and Ribbon
Motorized Y travel	stepback up to 7 mm (0,27"l)
Motorized Z travel	15 mm (0,6")
Throat depth	165 mm (6,7")
Fine Table motion	10 mm (0,55 ")
Mouse ratio	6:1 (Option 4:1 , 3:1)
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm (27")W x 640 mm (25") D x 490 mm (19") H
Weight	Shipping 60 kg Net 45 kg
Industry Standards	CE standards



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